## Remarkable Productivity and Performance of OLED Encapsulation through Growth dynamics control via Atmospheric Pressure Spatial Atomic Layer Deposition

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## **Supplemental Document**



Figure 1. (a) A schematic representation of the AP S-ALD system. (b) Establishment of four

process conditions with similar GPC values based on the evaluation of Al<sub>2</sub>O<sub>3</sub> growth behavior influenced by two factors affecting TMA exposure: substrate speed and TMA partial pressure. (c) The differences between the GPC of the four process conditions and the calculated GPC based on the Langmuir adsorption model, as well as the deposition rate. (d, e) Conceptual depiction of the differences in C-related impurity content within Al<sub>2</sub>O<sub>3</sub> and surface roughness, corresponding to the variations in GPC.



**Figure 2.** Evaluation results of Al<sub>2</sub>O<sub>3</sub> thin films grown under the four process conditions with varying differences in GPC for (a) water vapor transmission rate and (b) H<sub>2</sub> permeability. Barrier performance and deposition rate of Al<sub>2</sub>O<sub>3</sub> thin films grown using a hybrid process consisted with process conditions A and D.

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